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Intel® Edison Compute Module (IoT)

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PCN/MDDS Information

937637: PCN

Specifications

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⊖ Essentials

Status	Launched
Launch Date	Q3'14
# of QPI Links	0
Supported FSBs	N/A
FSB Parity	No
Board Form Factor	25mm x 35.5mm
Socket	70-pin Hirose .4mm
Extended Life Program (XLP)	No
Embedded Options Available	No
Lithography	22 nm
DC Input Voltage Supported	3.15V-4.5V
Back-to-BIOS Button	No
Recommended Customer Price	N/A
Description	Wi-Fi/BT Compute Module
Product Brief	Link
Additional Information URL	Link
Warranty Period	1 yrs

⊖ Memory Specifications

Max Memory Size (dependent on memory type)	4 GB
Memory Types	DDR3, NAND FLASH
Physical Address Extensions	32-bit
Max # of DIMMs	0
ECC Memory Supported ‡	No

⊖ I/O Specifications

USB Revision	USB 2.0
# of USB Ports	1
USB 2.0 Configuration (External + Internal)	1
USB 3.0 Configuration (External + Internal)	0
# of Serial Ports	2
Serial Port via Internal Header	Yes
Audio (back channel + front channel)	1 I2S
Integrated LAN	No
Integrated Wifi	Yes, 802.11n
Integrated Bluetooth	Yes
Firewire	No

⊖ Package Specifications

Max CPU Configuration	1
Package Size	25mm x 35.5mm
Low Halogen Options Available	See MDDS

⊖ Intel® Data Protection Technology

Intel® AES New Instructions	No

⊖ Intel® Platform Protection Technology

Trusted Execution Technology ‡	Yes
Anti-Theft Technology	No

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Refer to Datasheet for formal definitions of product properties and features.

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

Some products can support AES New Instructions with a Processor Configuration update, in particular, i7-2630QM/i7-2635QM, i7-2670QM/i7-2675QM, i5-2430M/i5-2435M, i5-2410M/i5-2415M. Please contact OEM for the BIOS that includes the latest Processor configuration update.

‡ This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

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System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

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